

3.5x2.8mm PLCC4 SMD LED

Features

- Ideal for indication light on hand held products
- Long life and robust package
- Variety of lens types and color choices available
- Standard Package: 2000pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- RoHS compliant.

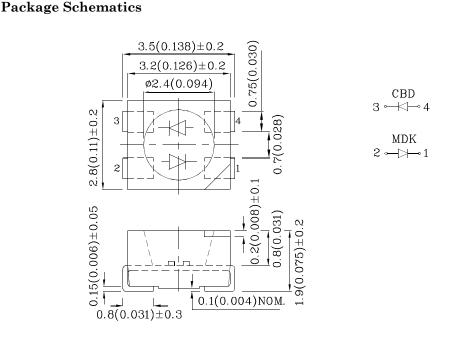




Part

Number

ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES



Notes:

1. All dimensions are in millimeters (inches).

2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.

3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		MDK (AlGaInP)	CBD (InGaN)	Unit
Reverse Voltage	V_{R}	5	5	V
Forward Current	$\mathbf{I}_{\mathbf{F}}$	30	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	$i_{\rm FS}$	185	150	mA
Power Dissipation	\mathbf{P}_{D}	75	120	mW
Electrostatic Discharge Threshold (HBM)		- 250		v
Operating Temperature	$T_{\rm A}$	-40 ~ +85		°C
Storage Temperature	Tstg	-40 ~ +85		

Operating Ch (T _A =25°C)	aracteristics		MDK (AlGaInP)	CBD (InGaN)	Unit	
Forward Voltag (I _F =20mA)	ge (Typ.)	V _F	1.95	3.3	v	
Forward Voltag (I _F =20mA)	V _F	2.5	4	v		
Reverse Curren (V _R =5V)	nt (Max.)	I_{R}	10	50	uA	
Wavelength of Emission CIE (I _F =20mA)	Peak 127-2007* (Typ.)	λP	$650 \\ 645^{*}$	468 460*	nm	
Wavelength of Emission CIE (I _F =20mA)	Dominant 127-2007* (Typ.)	λD	630 630*	470 465*	nm	
Spectral Line F At Half-Maxim (I _F =20mA)		$ riangle \lambda$	28	25	nm	
Capacitance (T (V _F =0V, f=1MH		С	35	100	pF	
Lens-color	Luminous Intensity CIE127-2007* (IF=20mA) mcd		Wavelengt CIE127-200 nm λP	07* View Ang	Viewing Angle 20 1/2	
	min.	typ.				
	200	917	650			

				min.	typ.		
XZMDKCBD45S	Red	AlGaInP	Water Clear –	200 55*	317 100*	$650 \\ 645^*$	- 120°
	Blue	InGaN		80 80*	148 150*	468 460*	

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards. Sep 19,2012

Emitting

Color

XDSB5016 V3-X Layout: Maggie L.

Emitting

Material

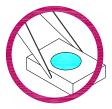
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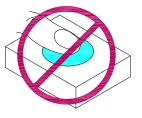
Handling Precautions

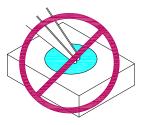
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

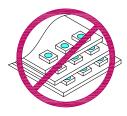


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



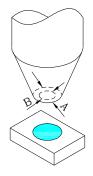


3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



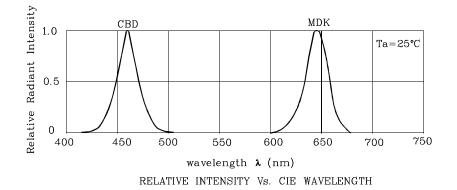
4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.

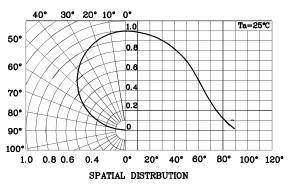
4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



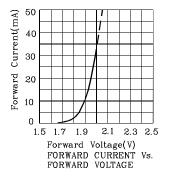
5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

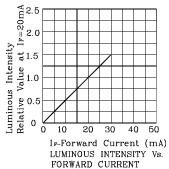


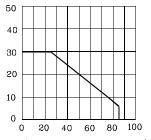




♦ MDK

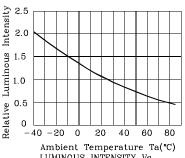






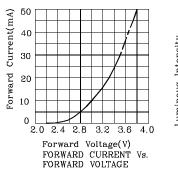
Forward Current(mA)

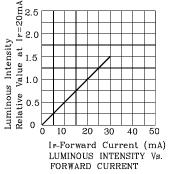
Ambient Temperature Ta(°C) FORWARD CURRENT DERATING CURVE

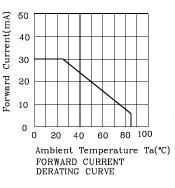


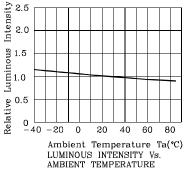


* CBD





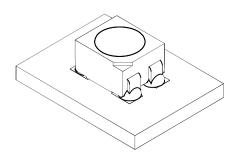




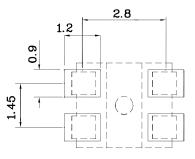


LED is recommended for reflow soldering and soldering profile is shown below.

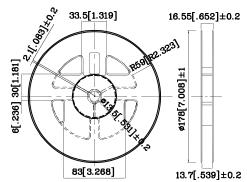
***** The device has a single mounting surface. The device must be mounted according to the specifications.



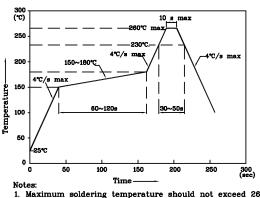
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension

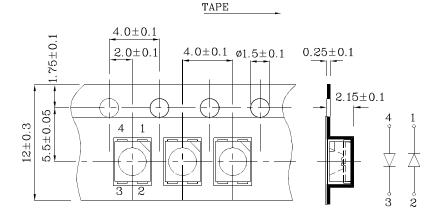


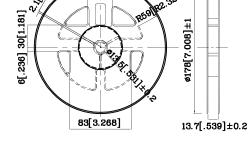
Reflow Soldering Profile for SMD Products (Pb-Free Components)



- Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C З. Do not put stress to the epoxy resin during
- high temperatures conditions

***** Tape Specification (Units : mm)





Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous intensity / luminous flux: +/-15%

3. Forward Voltage: +/-0.1V

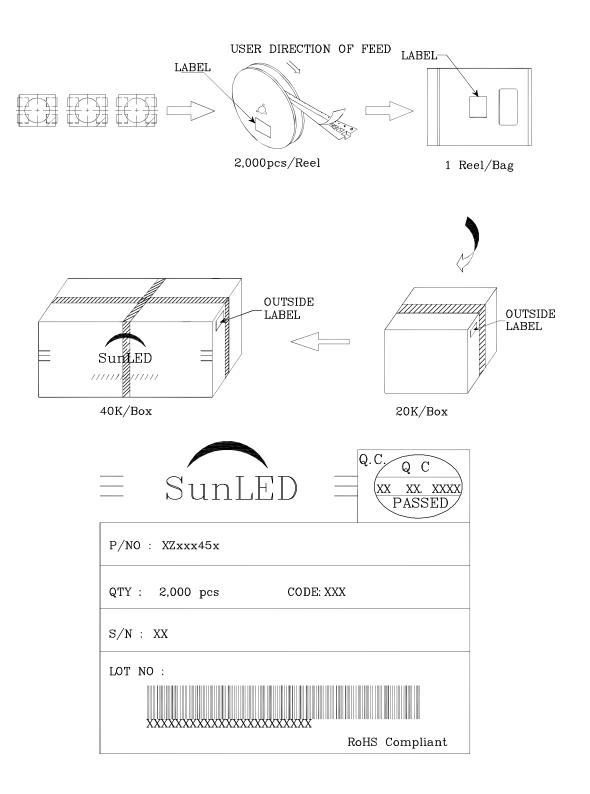
Note: Accuracy may depend on the sorting parameters.

Sep 19,2012

XDSB5016 V3-X Layout: Maggie L.



PACKING & LABEL SPECIFICATIONS



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